

Product Number: 122-10CC


122 Series Thermal Joint Compound is a stable, silicone based, thixotropic paste developed to provide premium performance at an affordable price. It is formulated to significantly reduce contact thermal resistance where power densities are concentrated in devices such as flip chip, reduced die size, and 'overclock' microprocessors. When applied as a thin film between a Wakefield heat sink and device it possesses superior thermal conductivity compared to traditional 'grease'. It is compatible with automated or manual dispensing methods and is fully RoHS compliant.

122 SERIES THERMAL JOINT COMPOUND	
Typical Characteristics	Description
Appearance	Smooth Gray paste
Thermal Conductivity	2.5 W / m °K, 17.3 (Btu) (in.)/(hr) (ft²) (°F)
Thermal Resistance	0.02 °C in 2 / W
Bleed	0.015 wt%, 24 hrs at 200°C
Evaporation	0.150 wt%, 24 hrs at 200°C
Volume Resistivity	1.4 x 10 ¹⁰ ohm-cm
Dielectric Strength	225 volts/mil
Specific Gravity	2.23 (gm/cc) at 25°C
Operating Range	-40°C to 205°C
Shelf Life	5 years

122 SERIES - ORDER GUIDE	
Series - P/N	Container Size
122-10CC	10cc syringe
122-2	2 oz (0.06 kg) jar
122-30CC	30cc syringe